

File No: 51-6 US CIP

DECLARATION FOR PATENT APPLICATION

RECEIVED

As below named inventors, we hereby declare that:

JUN 13 2000
TECHNOLOGY CENTER 2800

Our residence, post office addresses and citizenship are as stated below next to our names, **Theodore M. Garver and Hongqi Yuan.**

We believe we are the original, first and joint inventors of the subject matter which is claimed and for which a patent is sought on the invention entitled

**DETERMINATION OF THE PROPERTY OF A SOLUTION OR SOLID USING
RAMAN RATIOS**

the specification of which is attached hereto.

We hereby state that we have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of the Federal Regulations, S1.56(a).

We hereby state that this application in part discloses and claims subject matter disclosed in our earlier filed pending application Serial No: 08/814,519 filed March 10, 1997.

We hereby claim the benefit of Title 35, United States Code S119(e), of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is now disclosed in the prior United States patent application

(Number)	(Filing Date)	(Status) patented, pending, abandoned)
08/814,519	March 10, 1997	Pending

We hereby appoint the following agent to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Neil Teitelbaum	Regn No: 38,793
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor: Theodore M. GARVER

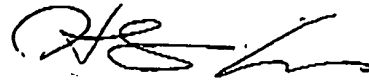
Inventor's signature *Theodore M. Garver* Date: *Jan 14, 2000*

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Citizenship: United States

Full name of second inventor:

Hongqi YUAN



Inventor's signature

Date:

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